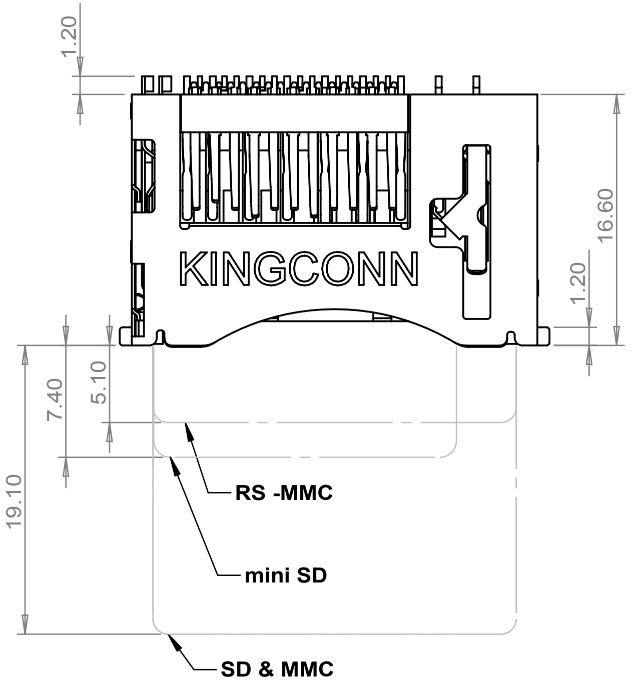
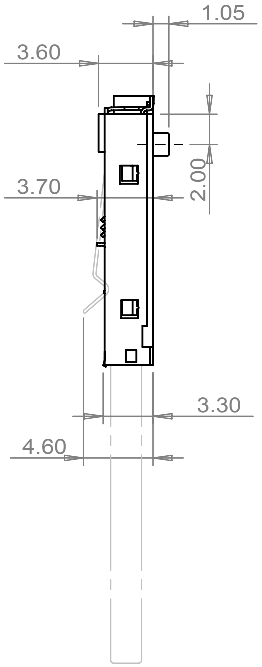
更改 REV	設 變 內 容 MODIFICATION
A	ECN00942
B	ECN04068



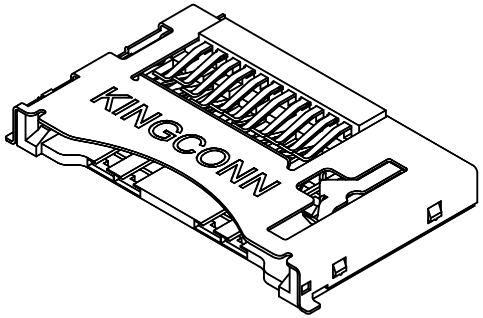


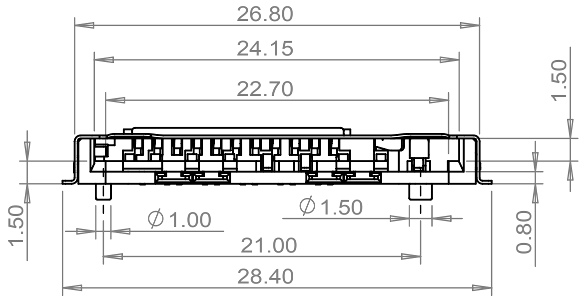
NOTES :
1. MATERIAL :
INSULATOR : HIGH TEMPERATURE
THERMOPLASTIC , UL94V-0.
COLOR : BLACK
CONTACT : PHOSPHOR BRONZE.

2. PART NO : SDMM-X0-0X15

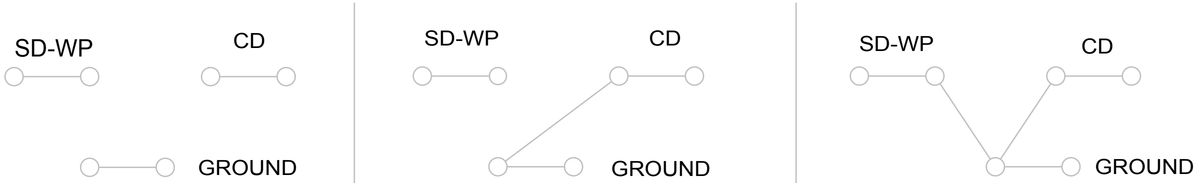
PACKING:
0 TARY
1 TAPE&REEL

PLATING :
F CONTACT AREA :Gold Flash Plated OVER Ni
SOLDER AREA : Tin Plated OVER Ni
B CONTACT AREA :10μ" Au Plated OVER Ni
SOLDER AREA : Tin Plated OVER Ni





CIRCUIT:



WITHOUT CARD

SD CARD INSERTED
WRITE PROTECT : LOCK

1.SD CARD INSERTED
WRITE PROTECT : UNLOCK
2.OTHER CARD INSERTED

GENERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.30	.X°± 2°
.XX± 0.20	.XX°± 1°
	.XXX°± 0.5°

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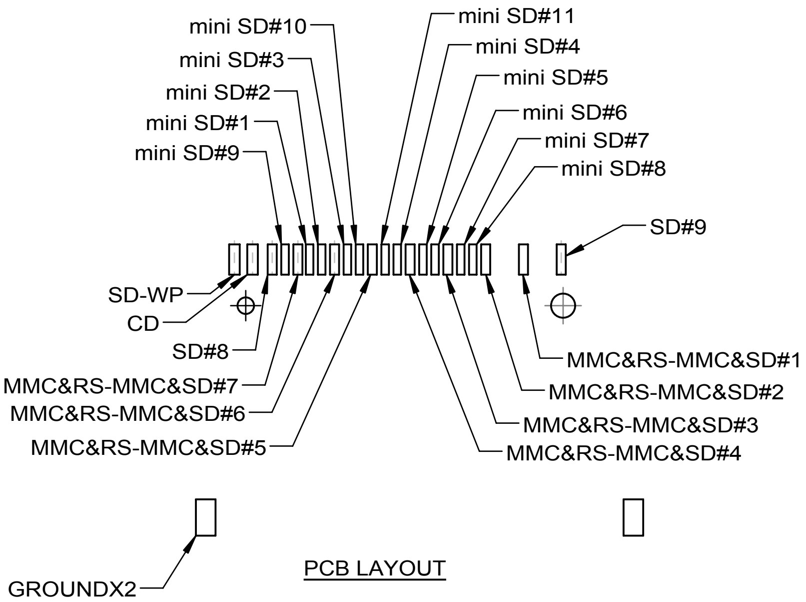
名 稱(TITLE)
4 IN 1(SD & miniSD & MMC & RS-MMC)
CARD CONNECTOR

單 位(UNIT)	料 號(PART NO.)	圖 號(DWG NO.)
mm	7SDMM-X0-0X15	7SDMM-X0-0X15-B

審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE	2:1	張 數 SHEET	1/2
			角 法 PROJ.		更 改 REV	B

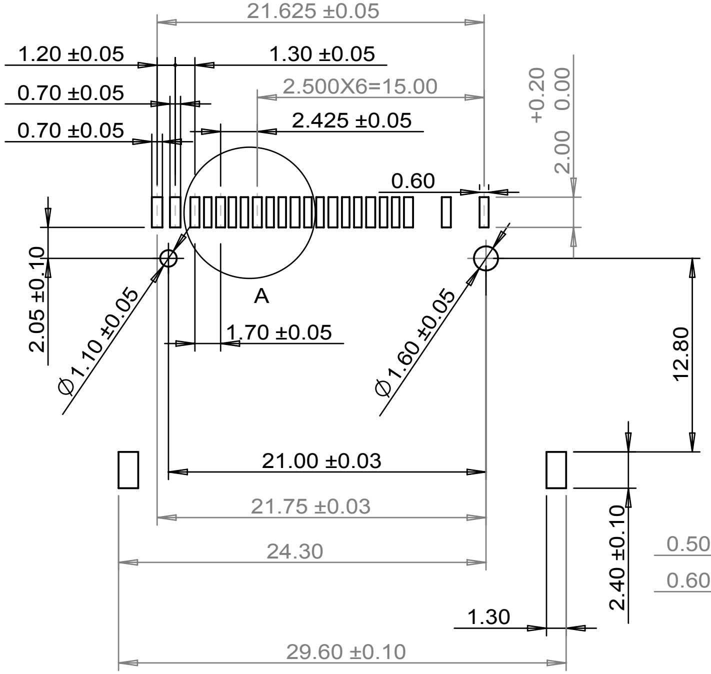
更改 REV	設 變 內 容 MODIFICATION
A	ECN00942
B	ECN04068



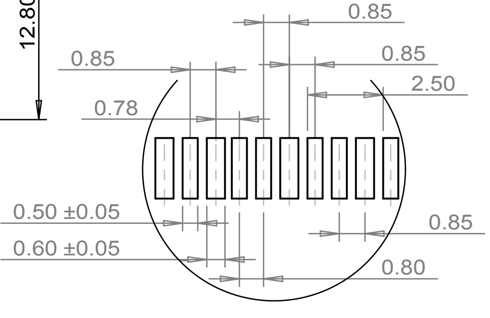
PCB LAYOUT

PIN ASSIGNMENT:

PIN NO.	MEMORY CARD PIN NO.
MMC&RS-MMC/SD#1	MMC&RS-MMC/SD-1 (RSV/DAT3)
MMC&RS-MMC&SD#2	MMC&RS-MMC&SD-2 (CMD)
MMC&RS-MMC&SD#3	MMC&RS-MMC&SD-3 (GND)
MMC&RS-MMC&SD#4	MMC&RS-MMC&SD-4 (VCC)
MMC&RS-MMC&SD#5	MMC&RS-MMC&SD-5 (CLK)
MMC&RS-MMC&SD#6	MMC&RS-MMC&SD-6 (GND)
MMC&RS-MMC&SD#7	MMC&RS-MMC&SD-7 (DAT0)
SD#8	SD-8 (DAT1)
SD#9	SD-9 (DAT2)
miniSD#1	miniSD-1 (CD/DAT3)
miniSD#2	miniSD-2 (CMD)
miniSD#3	miniSD-3 (GND)
miniSD#4	miniSD-4 (VCC)
miniSD#5	miniSD-5 (CLK)
miniSD#6	miniSD-6 (GND)
miniSD#7	miniSD-7 (DAT0)
miniSD#8	miniSD-8 (DAT1)
miniSD#9	miniSD-9 (DAT2)
miniSD#10	miniSD-10 (NC)
miniSD#11	miniSD-11 (NC)



PCB LAYOUT



A (4 : 1)

GENIERIAL TOLERANCE	
X.± 0.50	X.°± 5°
.X± 0.30	.X°± 2°
.XX± 0.20	.XX°± 1°
	.XXX°± 0.5°

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審 核(APPROVAL)	核 對(CHECKED)	製 圖(DRAWN)	比 例 SCALE	2 : 1	張 數 SHEET	2 / 2
			角 法 PROJ.		更 改 REV	B

QP-701-03